



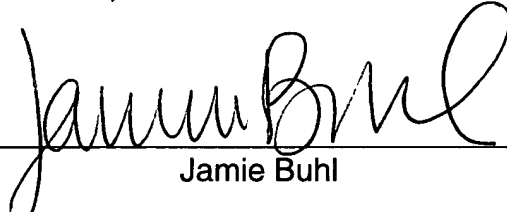
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Enzo CAROLLO
Title: HIGH-DENSITY PLASMA PROCESS FOR DEPOSITING A
LAYER OF SILICON NITRIDE
Serial Number: 10/686,556
Filing Date: October 14, 2003
Examiner/Unit: Timothy Howard Meeks/1762
Attorney Docket No.: 2110-81-3

Certificate of Mailing

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail and is addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 11th day of April, 2005.



Jamie Buhl

AMENDMENT AND RESPONSE UNDER 37 CFR §1.111

April 11, 2005

TO THE COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450:

Receipt of an Office Action mailed January 11, 2005 is acknowledged. Please amend the above-referenced patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.